

LM397 Single General Purpose Voltage Comparator

Check for Samples: [LM397](#)

FEATURES

- ($T_A = 25^\circ\text{C}$. Typical Values Unless Otherwise Specified).
- 5-Pin SOT-23 Package
- Industrial Operating Range -40°C to $+85^\circ\text{C}$
- Single or Dual Power Supplies
- Wide Supply Voltage Range 5V to 30V
- Low Supply Current 300 μA
- Low Input Bias Current 7nA
- Low Input Offset Current $\pm 1\text{nA}$
- Low Input Offset Voltage $\pm 2\text{mV}$
- Response Time 440ns (50mV Overdrive)
- Input Common Mode Voltage 0 to $V_S - 1.5\text{V}$

APPLICATIONS

- A/D Converters
- Pulse, Square Wave Generators
- Peak Detector
- Industrial Applications

Connection Diagram

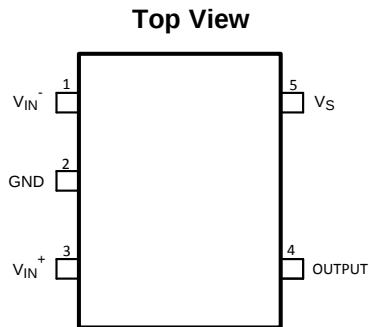


Figure 1. 5-Pin SOT-23 Package
See Package Number DBV0005A

Typical Circuit

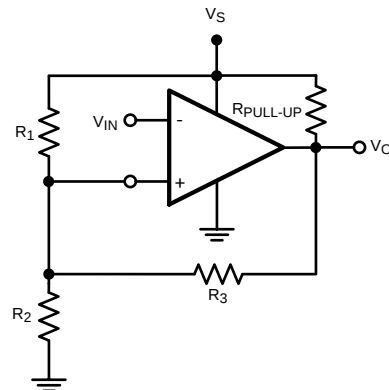


Figure 2. Inverting Comparator with Hysteresis



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



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Absolute Maximum Ratings ⁽¹⁾⁽²⁾

ESD Tolerance ⁽³⁾	Human Body Model	2KV
	Machine Model	200V
V _{IN} Differential		30V
Supply Voltages		30V or ±15V
Voltage at Input Pins		–0.3V to 30V
Storage Temperature Range		–65°C to +150°C
Junction Temperature ⁽⁴⁾		+150°C
Soldering Information	Infrared or Convection (20 sec.)	235°C
	Wave Soldering (10 sec.)	260°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.
- (3) Human Body Model, applicable std. MIL-STD-883, Method 3015.7. Machine Model, applicable std. JESD22-A115-A (ESD MM std. of JEDEC) Field-Induced Charge-Device Model, applicable std. JESD22-C101-C (ESD FICDM std. of JEDEC).
- (4) The maximum power dissipation is a function of T_{J(MAX)}, θ_{JA}. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)} - T_A) / θ_{JA}. All numbers apply for packages soldered directly onto a PC board.

Operating Ratings ⁽¹⁾

Supply Voltage, V _S		5V to 30V
Temperature Range ⁽²⁾		–40°C to +85°C
Package Thermal Resistance ⁽²⁾	5-Pin SOT-23	168°C/W

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics.
- (2) The maximum power dissipation is a function of T_{J(MAX)}, θ_{JA}. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)} - T_A) / θ_{JA}. All numbers apply for packages soldered directly onto a PC board.

Electrical Characteristics

Unless otherwise specified, all limits are guaranteed for $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, $V^- = 0\text{V}$, $V_{CM} = V^+/2 = V_O$. **Boldface** limits apply at the temperature extremes.

Parameter		Test Conditions	Min ⁽¹⁾	Typ ⁽²⁾	Max ⁽¹⁾	Units
V_{OS}	Input Offset Voltage	$V_S = 5\text{V to } 30\text{V}$, $V_O = 1.4\text{V}$, $V_{CM} = 0\text{V}$		2	7 10	mV
I_{OS}	Input Offset Current	$V_O = 1.4\text{V}$, $V_{CM} = 0\text{V}$		1.6	50 250	nA
I_B	Input Bias Current	$V_O = 1.4\text{V}$, $V_{CM} = 0\text{V}$		10	250 400	nA
I_S	Supply Current	$R_L = \text{Open}$, $V_S = 5\text{V}$		0.25	0.7	mA
		$R_L = \text{Open}$, $V_S = 30\text{V}$		0.30	2	
I_O	Output Sink Current	$V_{IN}^+ = 1\text{V}$, $V_{IN}^- = 0\text{V}$, $V_O = 1.5\text{V}$	6	13		mA
$I_{LEAKAGE}$	Output Leakage Current	$V_{IN}^+ = 1\text{V}$, $V_{IN}^- = 0\text{V}$, $V_O = 5\text{V}$		0.1		nA
		$V_{IN}^+ = 1\text{V}$, $V_{IN}^- = 0\text{V}$, $V_O = 30\text{V}$		1		μA
V_{OL}	Output Voltage Low	$I_O = -4\text{mA}$, $V_{IN}^+ = 0\text{V}$, $V_{IN}^- = 1\text{V}$		180	400 700	mV
V_{CM}	Common-Mode Input Voltage Range	$V_S = 5\text{V to } 30\text{V}$ ⁽³⁾	0 0		$V_S - 1.5\text{V}$ $V_S - 2\text{V}$	V
A_V	Voltage Gain	$V_S = 15\text{V}$, $V_O = 1.4\text{V to } 11.4\text{V}$, $R_L \geq 15\text{k}\Omega$ connected to V_S		120		V/mV
t_{PHL}	Propagation Delay (High to Low)	Input Overdrive = 5mV $R_L = 5.1\text{k}\Omega$ connected to 5V, $C_L = 15\text{pF}$		900		ns
		Input Overdrive = 50mV $R_L = 5.1\text{k}\Omega$ connected to 5V, $C_L = 15\text{pF}$		250		
t_{PLH}	Propagation Delay (Low to High)	Input Overdrive = 5mV $R_L = 5.1\text{k}\Omega$ connected to 5V, $C_L = 15\text{pF}$		940		μs
		Input Overdrive = 50mV $R_L = 5.1\text{k}\Omega$ connected to 5V, $C_L = 15\text{pF}$		440		ns

- (1) All limits are guaranteed by testing or statistical analysis.
- (2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.
- (3) The input common-mode voltage of either input should not be permitted to go below the negative rail by more than 0.3V. The upper end of the common-mode voltage range is $V_S - 1.5\text{V}$ at 25°C .

Typical Performance Characteristics

$T_A = 25^\circ\text{C}$. Unless otherwise specified.

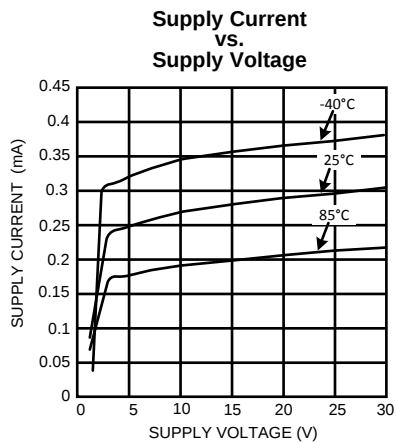


Figure 3.

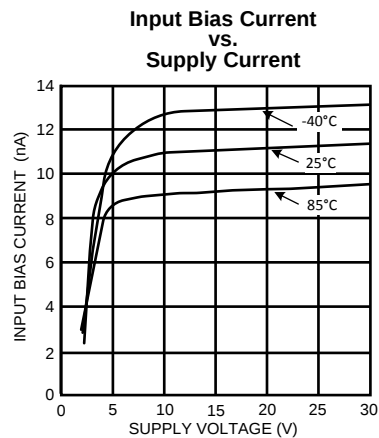


Figure 4.

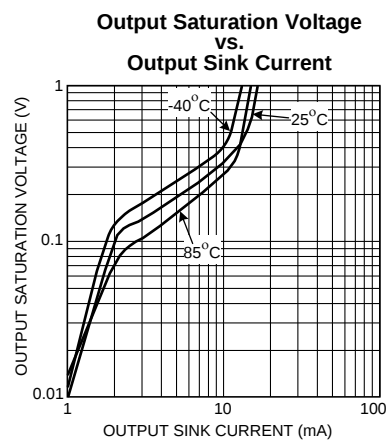


Figure 5.

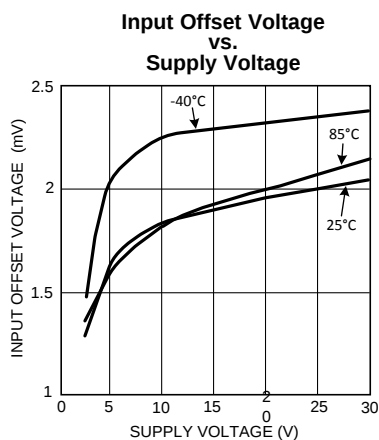


Figure 6.

Response Time for Various Input Overdrives – t_{PHL}

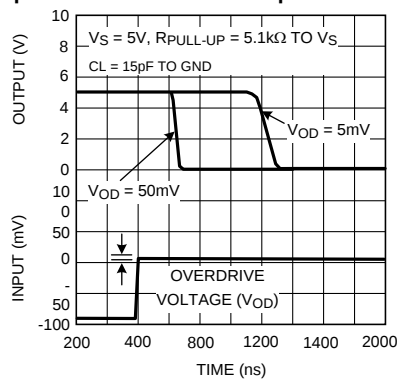


Figure 7.

Response Time for Various Input Overdrives – t_{PLH}

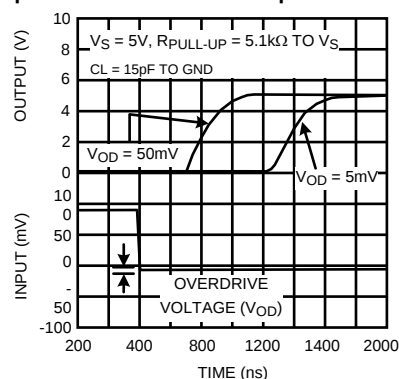


Figure 8.

APPLICATION NOTES

Basic Comparators

A comparator is quite often used to convert an analog signal to a digital signal. The comparator compares an input voltage (V_{IN}) at the non-inverting pin to the reference voltage (V_{REF}) at the inverting pin. If V_{IN} is less than V_{REF} the output (V_O) is low (V_{OL}). However, if V_{IN} is greater than V_{REF} , the output voltage (V_O) is high (V_{OH}). Refer to Figure 9.

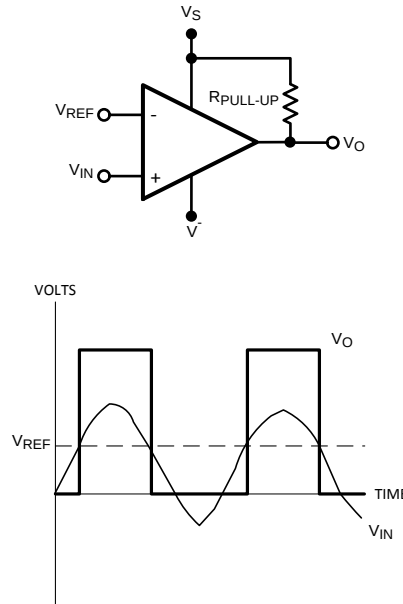


Figure 9. Basic Comparator

Hysteresis

The basic comparator configuration may oscillate or produce a noisy output if the applied differential input is near the comparator's input offset voltage. This tends to occur when the voltage on the input is equal or very close to the other input voltage. Adding hysteresis can prevent this problem. Hysteresis creates two switching thresholds (one for the rising input voltage and the other for the falling input voltage). Hysteresis is the voltage difference between the two switching thresholds. When both inputs are nearly equal, hysteresis causes one input to effectively move quickly pass the other. Thus, effectively moving the input out of region that oscillation may occur.

For an inverting configured comparator, hysteresis can be added with a three resistor network and positive feedback. When input voltage (V_{IN}) at the inverting node is less than non-inverting node (V_T), the output is high. The equivalent circuit for the three resistor network is R_1 in parallel with R_3 and in series with R_2 . The lower threshold voltage V_{T1} is calculated by:

$$V_{T1} = ((V_S R_2) / (((R_1 R_3) / (R_1 + R_3)) + R_2)) \quad (1)$$

When V_{IN} is greater than V_T , the output voltage is low. The equivalent circuit for the three resistor network is R_2 in parallel with R_3 and in series with R_1 . The upper threshold voltage V_{T2} is calculated by:

$$V_{T2} = V_S ((R_2 R_3) / (R_2 + R_3)) / (R_1 + ((R_2 R_3) / (R_2 + R_3))) \quad (2)$$

The hysteresis is defined as

$$\Delta V_{IN} = V_{T1} - V_{T2} \quad (3)$$

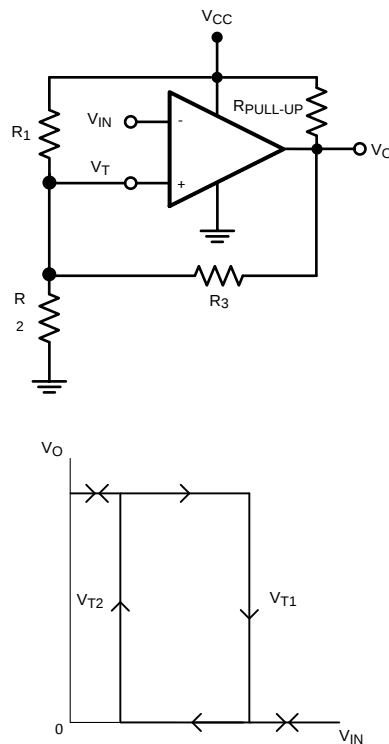


Figure 10. Inverting Configured Comparator - LM397

Input Stage

The LM397 has a bipolar input stage. The input common mode voltage range is from 0 to ($V_S - 1.5V$).

Output Stage

The LM397 has an open collector grounded-emitter NPN output transistor for the output stage. This requires an external pull-up resistor connected between the positive supply voltage and the output. The external pull-up resistor should be high enough resistance so to avoid excessive power dissipation. In addition, the pull-up resistor should be low enough resistance to enable the comparator to switch with the load circuitry connected. Because it is an open collector output stage, several comparator outputs can be connected together to create an OR'ing function output. With an open collector, the output can be used as a simple SPST switch to ground. The amount of current which the output can sink is approximately 10mA. When the maximum current limit is reached, the output transistor will saturate and the output will rise rapidly (Figure 11).

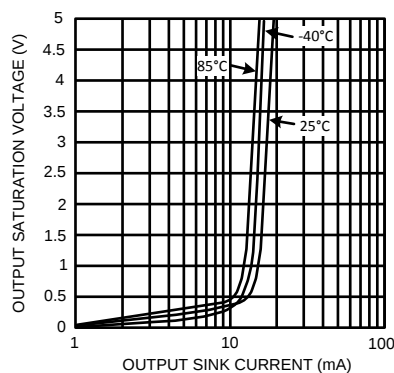


Figure 11. Output Saturation Voltage vs. Output Sink Current

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM397MF	ACTIVE	SOT-23	DBV	5	1000	TBD	CU SNPB	Level-1-260C-UNLIM	-40 to 85	C397	Samples
LM397MF/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	C397	Samples
LM397MFX	ACTIVE	SOT-23	DBV	5	3000	TBD	CU SNPB	Level-1-260C-UNLIM	-40 to 85	C397	Samples
LM397MFX/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	C397	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM397MF	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM397MF/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM397MFX	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM397MFX/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS

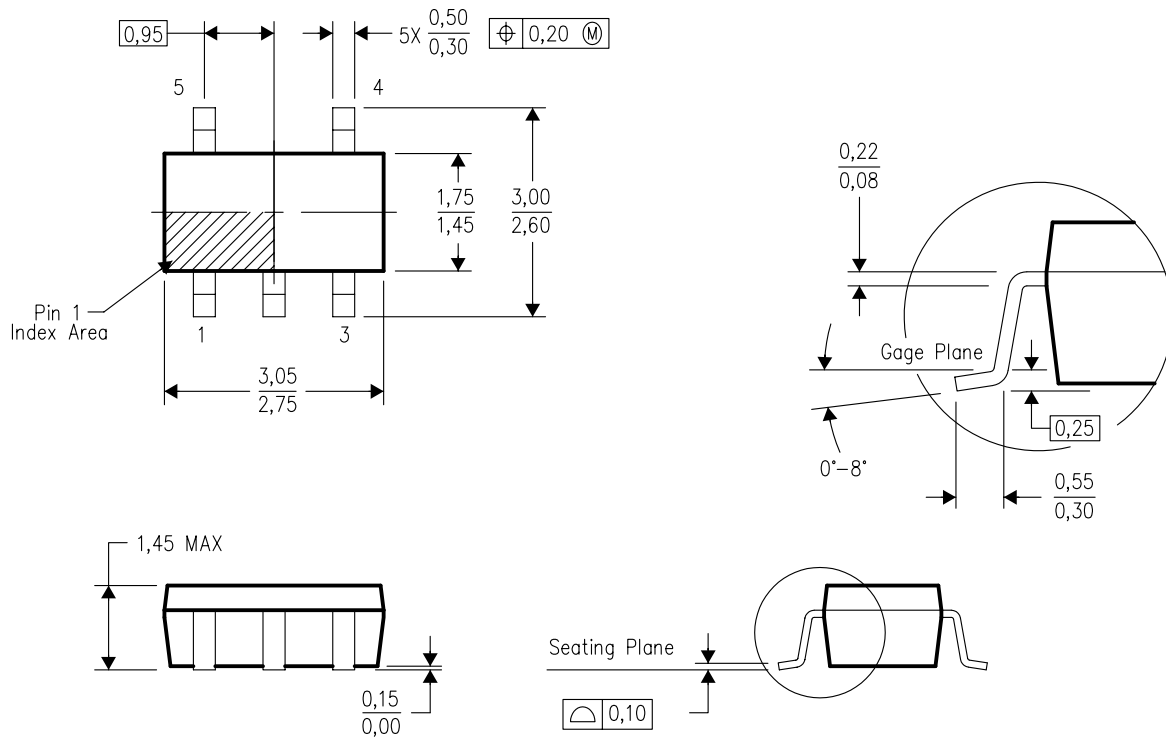


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM397MF	SOT-23	DBV	5	1000	203.0	190.0	41.0
LM397MF/NOPB	SOT-23	DBV	5	1000	203.0	190.0	41.0
LM397MFX	SOT-23	DBV	5	3000	206.0	191.0	90.0
LM397MFX/NOPB	SOT-23	DBV	5	3000	206.0	191.0	90.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE

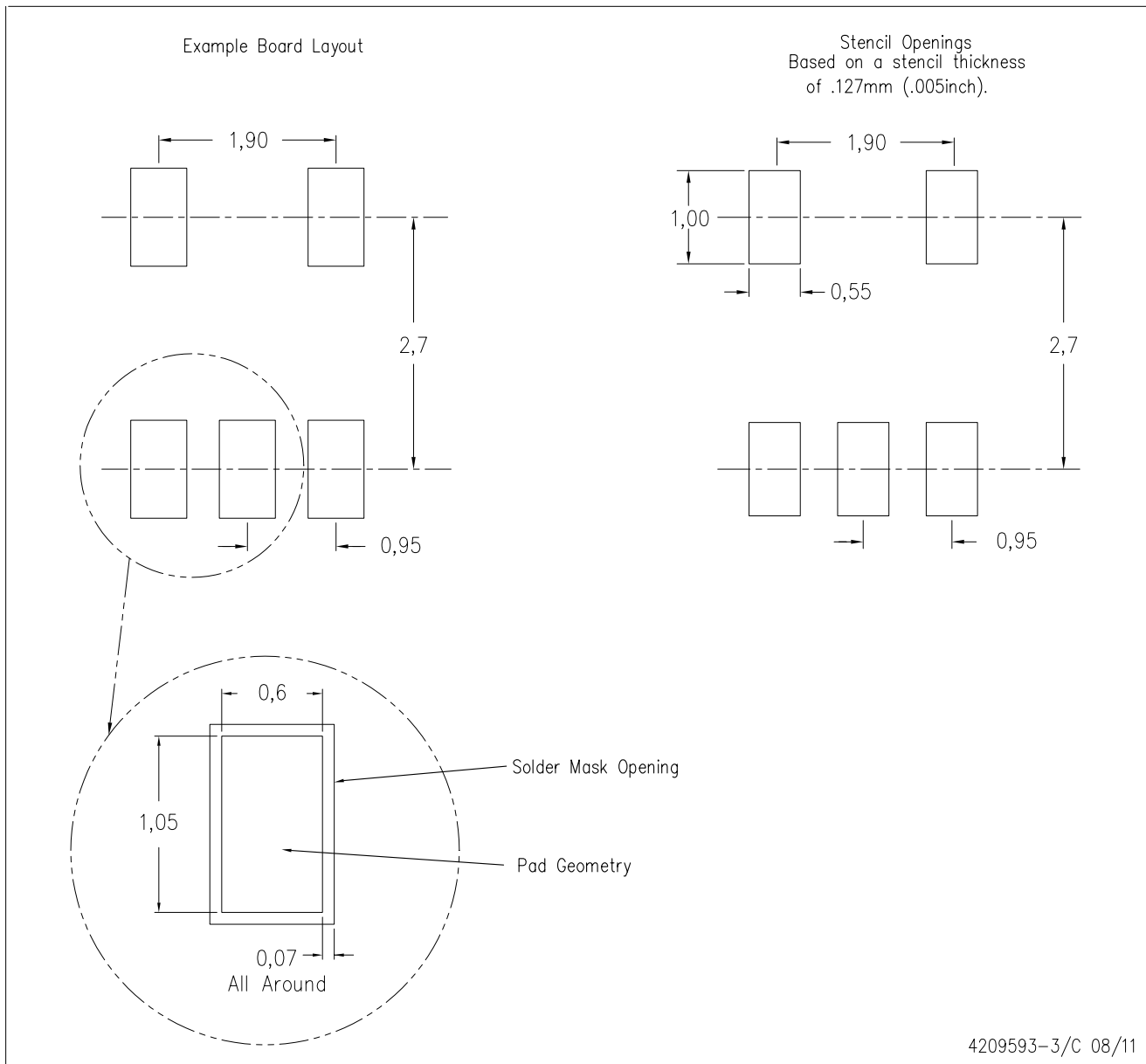


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- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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